

Introduction

Temasek Financial (IV) Private Limited is the issuer of the T2026-S\$ Temasek Bond, initially comprising:

- a Placement of S\$250 million to institutional, accredited and other specified investors;
- a Public Offer of up to S\$100 million to retail investors in Singapore.

Temasek fully guarantees all interest payments of the T2026-S\$ Temasek Bond and full repayment of the principal amount at maturity.

Bids from institutional, accredited and other specified investors in a bookbuilding process were used to determine the interest rate for the T2026-S\$ Temasek Bond.

The same interest rate was offered to retail investors in the Public Offer.

In view of the demand from retail investors, the Issuer and Temasek have decided to increase the issue size by S\$150 million for the Public Offer. The total issue size of \$\$500 million is allocated as shown below:

Allocation of the T2026-S\$ Temasek Bond

Placement to institutional, accredited and other specified investors

Total size : S\$250 million Bids received : about S\$1,542 million

Public Offer to retail investors in Singapore

Total size : S\$250 million Valid applications received : about S\$649 million

Successful applicants in the Public Offer will have their T2026-S\$ Temasek Bond allocations credited to their respective CDP accounts on 24 Nov 2021.

Applicants with invalid or partially successful applications will have their respective balances refunded starting from 23 Nov 2021, into their designated bank account.

All applicants who submitted valid applications under the Public Offer of S\$250 million have been allocated all or a proportion of the bonds they applied for.

Key Dates For applicants who did not receive their full allocations, refunds to their bank accounts will begin, in full or in part as appropriate. Issue date. 24 Nov 2021 Retail investors can check their allocations in their CDP accounts. 24 Nov 2021 Expected start of trading on the Main Board of SGX-ST at 9:00 am. Thu The Trading Name for the bonds will be Temasek 1.8% 261124XB# 25 Nov 2021 and the SGX-ST stock code will be TEMB.

First interest payment. All payments will be made on or around 24 May and 24 Nov each year, until maturity in Nov 2026.

Amount of Public Offer bonds applied for (S\$)	Public Offer bonds allocated per successful applicant (S\$)	Percentage allocated under the Public Offer (%)	Number of successful Public Offer applicants
1,000	1,000	0.13	327
2,000	2,000	0.38	473
3,000	3,000	0.49	412
4,000	4,000	0.25	155
5,000	5,000	3.50	1,751
6,000	6,000	0.89	370
7, 000	7, 000	0.29	102
8,000	8,000	1.00	311
9,000	9,000	0.13	35
10,000	10,000	15.87	3,968
11,000	11,000	1.09	247
12,000	12,000	0.85	178
13,000	13,000	0.10	19
14,000 to 49,000	13,000	31.89	6,133
50,000 to 69,000	16,000	16.15	2,524
70,000 to 99,000	20,000	2.79	349
100,000 to 249,000	30,000	18.94	1,578
250,000 to 499,000	50,000	3.32	166
500,000 to 749,000	66,000	1.21	46
750,000 to 999,000	95,000	0.23	6
1,000,000 to 1,670,000	105,000	0.50	12
Total		100	19,162

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Tue

24 May 2022